

[54] HEAT-CURABLE ORGANOPOLYSILOXANE COMPOSITIONS

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[57] ABSTRACT

Heat-curable organopolysiloxane compositions comprising a diorganopolysiloxane having at least two vinyl groups per molecule and a viscosity exceeding 100 centistokes at 25° C, an inorganic filler, an organohydrogenpolysiloxane containing at least two Si—H linkages per molecule, a platinum catalyst, a hydrazine compound and optionally, an organic peroxide, which have an improved storage stability and allow for imparting an excellent flame retardancy and mechanical strength to the cured material.

11 Claims, No Drawings